L Number	Hits		DB	Time stamp
-	1962	134/1.ccls.	USPAT;	2004/09/23 11:32
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	50570	/-h	IBM_TDB	
-	59579	(shower adj head) or diffuser	USPAT;	2004/09/23 11:33
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
_	5651	(wafer or semiconductor) and ((shower adj	IBM_TDB	0001/00/00
	3031	head) or diffuser)	USPAT;	2004/09/23 11:42
		neudy of diffusely	US-PGPUB; EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	174	WF6 and SiH4	USPAT;	2004/09/23 11:43
			US-PGPUB;	2004/05/25 11.45
1			EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	6	((wafer or semiconductor) and ((shower adj	USPAT;	2004/09/23 11:46
		head) or diffuser)) and (WF6 and SiH4)	US-PGPUB;	
]			EPO; JPO;	
			DERWENT;	
_	1803	IME out 61 and 1010 and 41	IBM_TDB	
	1003	'WF.sub.6' and 'SiH.sub.4'	USPAT;	2004/09/23 11:50
			US-PGPUB;	· ·
			EPO; JPO; DERWENT;	
			IBM TDB	
-	137	((shower adj head) or diffuser) and	USPAT;	2004/09/23 11:52
		('WF.sub.6' and 'SiH.sub.4')	US-PGPUB;	=====================================
			EPO; JPO;	
			DERWENT;	
	100		IBM_TDB	
-	103	(((shower adj head) or diffuser) and	USPAT;	2004/09/23 11:53
		('WF.sub.6' and 'SiH.sub.4')) and clean\$3	US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	
-	1	((((shower adj head) or diffuser) and	USPAT;	2004/09/23 12:23
		('WF.sub.6' and 'SiH.sub.4')) and clean\$3)	US-PGPUB;	2001/03/23 12:23
		and (showerhead or diffuser) same (cool\$3)	EPO; JPO;	
			DERWENT;	
	0216		IBM_TDB	
-	2316	remote adj plasma	USPAT;	2004/09/23 12:23
į			US-PGPUB;	
			EPO; JPO;	
			DERWENT; IBM TDB	
-	111	(remote adj plasma) and ('WF.sub.6' and	USPAT;	2004/09/23 12:28
j l		'SiH.sub.4')	US-PGPUB;	2001/05/25 12.20
	j		EPO; JPO;	•
			DERWENT;	
			IBM_TDB	
-	8	((remote adj plasma) and ('WF.sub.6' and	USPAT;	2004/09/23 13:01
	. 1	'SiH.sub.4')) and 134/\$.ccls.	US-PGPUB;	•
	ļ	•	EPO; JPO;	,
			DERWENT;	
-	38	134/1.ccls. and ((shower adj head) or	IBM_TDB USPAT;	2004/09/23 14:01
		diffuser)	US-PGPUB;	2004/03/23 14:01
'		·	EPO; JPO;	,
	Į		DERWENT;	
			IBM TDB	
- '	52	((remote adj plasma) and ('WF.sub.6' and	USPAT;	2004/09/23 14:34
!		'SiH.sub.4')) and ((showerhead or	US-PGPUB;	
		dispenser or diffuser) same (temperature	EPO; JPO;	
		or heat\$3 or cool\$3))	DERWENT;	
	L		IBM TDB	

_	51	'SiH.sub.4')) and ((showerhead or	USPAT; US-PGPUB;	2004/09/23 14:50
		dispenser or diffuser) same (temperature or heat\$3 or cool\$3))) and clean\$3	EPO; JPO; DERWENT;	
			IBM TDB	
-	266	134/1.ccls. and (clean\$3 and (chamber or	USPAT;	2004/09/23 14:51
		apparatus)).ti.	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
- `	998	134/1.ccls. and method.ti.	IBM_TDB USPAT;	2004/00/02 14 50
		201/1.0013. and meenod. cr.	US-PGPUB;	2004/09/23 14:52
		·	EPO; JPO;	
			DERWENT;	
_	165	/13//1 ==1= === / 3	IBM_TDB	
_	165	(134/1.ccls. and (clean\$3 and (chamber or apparatus)).ti.) and method.ti.	USPAT;	2004/09/23 14:52
		apparatus//.tr./ and method.tr.	US-PGPUB; EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	76	1 (1-4-) 11-0010; and (01-041145) and (Chambel Of	USPAT;	2004/09/23 15:12
		apparatus)).ti.) and method.ti.) and (wafer or semiconductor)	US-PGPUB;	
		(water of Semiconductor)	EPO; JPO;	
			DERWENT; IBM TDB	,
	488	134/1.1.ccls.	USPAT;	2004/09/23 15:12
			US-PGPUB;	2001,00,00 10.12
			EPO; JPO;	
1			DERWENT;	
	78	134/1.1.ccls. and (remote adj plasma)	IBM_TDB USPAT;	2004/00/22 15 12
		101/1:1:0010: and (10mote ad) plasma)	US-PGPUB;	2004/09/23 15:13
			EPO; JPO;	
			DERWENT;	
_	33	134/1.1.ccls. and ((shower adj head) or	IBM_TDB	0004/00/00
		diffuser)	USPAT; US-PGPUB;	2004/09/23 15:17
		·	EPO; JPO;	
		· ·	DERWENT;	•
_	1	134/1.ccls. and (heat\$3 near showerhead)	IBM_TDB	
	1	134/1.ccis. and (neal\$3 near snowernead)	USPAT; US-PGPUB;	2004/09/23 15:21
!			EPO; JPO;	
			DERWENT;	
		124/1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1	IBM_TDB	
_	3	134/1.1.ccls. and heat\$3 near showerhead	USPAT;	2004/09/23 15:21
			US-PGPUB; EPO; JPO;	
			DERWENT;	
		124/1 1 1 1	IBM_TDB	
_	3	134/1.1.ccls. and (heat\$3 near showerhead)	USPAT;	2004/09/23 15:31
]		US-PGPUB;	`
		~	EPO; JPO; DERWENT;	
			IBM TDB	
-	17		USPĀT;	2004/09/23 15:32
	[or diffuser or distribut\$3))	US-PGPUB;	
			EPO; JPO; DERWENT;	
•			IBM TDB	
-	1541008	wafer or semiconductor	USPAT;	2004/09/24 08:09
			US-PGPUB;	,
			EPO; JPO;	
			DERWENT; IBM TDB	
_	0	(wafer or semiconductor) and (((shower adj	USPAT;	2004/09/24 08:11
		head) or diffuser) near (cool\$3 near	US-PGPUB;	, , , , , , , , , , , , , , , , , , , ,
		solution))	EPO; JPO;	
		·	DERWENT;	
			IBM TDB	

c				
-	13	Tributed of semiconductor, and ((Shower	USPAT;	2004/09/24 08:12
	j	adj head) or diffuser) near cool\$3)) and	US-PGPUB;	
	İ	clean\$3	EPO; JPO;	
	ļ		DERWENT;	
			IBM TDB	4
-	33	(wafer or semiconductor) and (((shower adj	_	2004/20/24 22 11
		head) or diffuser) near cool\$3)	USPAT;	2004/09/24 08:14
	1	head, of diffuser, hear coorss)	US-PGPUB;	
		•	EPO; JPO;	1
		,	DERWENT;	
			IBM TDB	
-	345	134/1.2.ccls.	USPAT;	2004/09/24 08:58
			US-PGPUB;	
			EPO; JPO;	
			DERWENT:	
			IBM TDB	
-	23	134/1.2.ccls. and showerhead	USPAT;	2004/00/04 00 03
		and showerhead	1	2004/09/24 09:27
i	1		US-PGPUB;	
ŀ			EPO; JPO;	
			DERWENT;	
	1.00		IBM TDB	
_	197	216/69.ccls.	USPAT;	2004/09/24 09:30
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
,			IBM TDB	j
-	10	216/69.ccls. and (showerhead or diffuser	USPAT;	2004/00/24 10 00
		or (diffusion near plate))		2004/09/24 10:22
	1	or (arragion near brace))	US-PGPUB;	}
			EPO; JPO;	
			DERWENT;	
1		110/702	IBM_TDB	
-	0	118/723.ccls.	USPĀT;	2004/09/24 10:22
1			US-PGPUB;	[
1			EPO; JPO;	
			DERWENT;	į l
	1		IBM TDB	
-	1341	118/723e.ccls.	USPAT;	2004/09/24 10:23
			US-PGPUB;	2004/03/24 10:23
	1		EPO; JPO;	j l
	1		DERWENT;	
	68415	should be to the	IBM_TDB	
	00413	showerhead or (shower adj head) or	USPAT;	2004/09/24 10:24
		diffuser or (diffusion adj plate)	US-PGPUB;	1
		,	EPO; JPO;	
		·	DERWENT;	·
	1		IBM TDB	
-	239		USPĀT;	2004/09/24 10:24
		adj head) or diffuser or (diffusion adj	US-PGPUB;	2004/05/24 10:24
		plate))		
			EPO; JPO;	,
			DERWENT;	
I _	21	(119/7220 pole and (1)	IBM_TDB	
1] 21	(118/723e.ccls. and (showerhead or (shower	USPAT;	2004/09/24 11:01
	1 1	adj head) or diffuser or (diffusion adj	US-PGPUB;	
1		plate))) and ((shower adj head) or	EPO; JPO;	`
]	diffuser or (diffusion adj plate)) same	DERWENT;	
		cool\$3	IBM TDB	
-	8422	(showerhead or (shower adj head) or	USPAT;	2004/09/24 11:02
1		diffuser or (diffusion adj plate)) and	US-PGPUB;	2301/03/24 11.02
		(wafer or semiconductor)	EPO; JPO;	·
			DERWENT;	
_	91	((showerhead or /shower add)	IBM_TDB	
) 31	((showerhead or (shower adj head) or	USPAT;	2004/09/24 11:04
		diffuser or (diffusion adj plate)) and	US-PGPUB;	
		(wafer or semiconductor)) and ((shower adj	EPO; JPO;	
		head) or diffuser or (diffusion adi	DERWENT;	·
		plate)) near (temperature or '.deg (')	IBM TDB	ŀ
-	91	((showerhead or (shower adi head) or	USPAT;	2004/09/24 11:13
i		diffuser or (diffusion adj plate)) and	US-PGPUB;	-501,05,24 11.15
		(wafer or semiconductor)) and ((shower adj	EPO; JPO;	1
		head) or diffuser or (diffusion adj	DERWENT;	
		plate)) near (temperature or '.degree.C')		•
——	L		IBM TDB	

_	8	US-5935340-\$.DID. OR US-6251776-\$.DID. OR US-6417080-\$.DID. OR US-6492276-\$.DID.	USPAT; US-PGPUB;	2004/09/24 11:20
			EPO; JPO; DERWENT;	
-	257	438/905.ccls.	IBM_TDB USPAT;	2004/09/24 11:20
			US-PGPUB; EPO; JPO;	
			DERWENT; IBM TDB	ŕ
_	200	438/905.ccls. and plasma	USPAT; US-PGPUB;	2004/09/24 11:20
			EPO; JPO;	
	21	((420/005	DERWENT; IBM_TDB	
	21	and (showerhead or diffuser or (diffusion	USPAT; US-PGPUB;	2004/09/24 11:55
		near plate))	EPO; JPO; DERWENT;	
-	65	"5788799"	IBM_TDB USPAT;	2004/09/24 11:55
			US-PGPUB; EPO; JPO;	
			DERWENT; IBM TDB	
-	2	5788799.did.	USPAT; US-PGPUB;	2004/09/24 11:58
			EPO; JPO; DERWENT;	
_	164	156/345.46.ccls.	IBM_TDB	0004/00/04
	POI	150/545.40.0015.	USPAT; US-PGPUB;	2004/09/24 11:59
			EPO; JPO; DERWENT;	
-	65877		IBM_TDB USPAT;	2004/09/24 11:59
		adj head) or diffuser or (diffusion adj plate)	US-PGPUB; EPO; JPO;	
			DERWENT; IBM TDB	
	39	(shower adj head) or diffuser or	USPAT; US-PGPUB;	2004/09/24 13:37
		(diffusion adj plate))	EPO; JPO; DERWENT;	
_	4	US-4960488-\$.DID. OR US-5939831-\$.DID.	IBM_TDB USPAT;	2004/09/24 13:38
			US-PGPUB; EPO; JPO;	20100
			DERWENT; IBM TDB	
-	57	(438/905.ccls. and plasma) and microwave	USPAT; US-PGPUB;	2004/09/24 14:44
			EPO; JPO; DERWENT;	
_	1	"5252178".PN.	IBM TDB USPAT;	2004/00/24 14 22
_	1	"5356478".PN.	US-PGPUB	2004/09/24 14:33
		"6569257".PN.	USPAT; US-PGPUB	2004/09/24 14:34
_	730	134/19.ccls.	USPAT; US-PGPUB	2004/09/24 14:36
	/30	194/19.CCIS.	USPAT; US-PGPUB;	2004/09/24 14:44
			EPO; JPO; DERWENT;	
-	165	134/19.ccls. and (semiconductor or wafer)	IBM_TDB USPAT;	2004/09/24 14:46
			US-PGPUB; EPO; JPO;	
	1	·	DERWENT; IBM TDB	

		1 (104/10		
-	21	(134/19.ccls. and (semiconductor or	USPAT;	2004/09/24 14:48
		wafer)) and microwave	US-PGPUB;	
			EPO; JPO;	
		·	DERWENT;	
			IBM_TDB	
-	257	438/905.ccls.	USPAT;	2004/09/24 16:12
			US-PGPUB;	
			EPO; JPO;	
		·	DERWENT;	
			IBM TDB	
-	0	438/905.ccls. and (microwave not plasma)	USPAT;	2004/09/24 14:49
		•	US-PGPUB;	
		, .	EPO; JPO;	
		· ·	DERWENT;	
			IBM TDB	
_	57	438/905.ccls. and microwave	USPAT;	2004/09/24 14:49
			US-PGPUB;	2003/05/24 14.49
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
~	0	156/345.36.ccls. and (microwave not		2004/00/24 14 50
		plasma)	USPAT;	2004/09/24 14:50
		(Prasma)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
_	74	156/345.36.ccls.	IBM_TDB	
	/4	130/343.36.CCIS.	USPAT;	2004/09/24 14:52
			US-PGPUB;	
			EPO; JPO;]
			DERWENT;	
	_	CC25117 11 1	IBM_TDB	
	2	6635117.did.	USPAT;	2004/09/24 14:52
			US-PGPUB;]
		, ·	EPO; JPO;	
	i		DERWENT;	
		400 400	IBM_TDB	
-	77	438/905.ccls. and tungsten	USPAT;	2004/09/24 16:12
			US-PGPUB;	
			EPO; JPO;	
		•	DERWENT;	- 1
			IBM TDB	
-	46	(438/905.ccls. and tungsten) and fluorine	USPAT;	2004/09/24 16:15
	·	-	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	· ·
			IBM TDB	
-	20	((438/905.ccls. and tungsten) and fluorine	USPAT;	2004/09/24 16:15
) and microwave	US-PGPUB;	2001/03/24 10.13
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
			T DM I DD	